

# Material Declaration Report

Package Type:	SOIC 24L (300mil)
Pericom Package Code:	S24(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	626.230
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

## Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	453.697	OSE	Silica Fused	60676-86-0	90.800	411.9572
			Epoxy Resin 1	Proprietary	3.000	13.6109
			Phenolic Resin	Proprietary	3.000	13.6109
			Epoxy Resin 2	Proprietary	2.000	9.0739
			Aromatic Phosphate	Proprietary	1.000	4.5370
			Carbon Black	1333-86-4	0.200	0.9074
			Copper	7440-50-8	97.021	158.4248
LEADFRAME	163.290		Iron	7439-89-6	2.350	3.8373
			Silver	7440-22-4	0.453	0.7402
			Zinc	7440-66-6	0.111	0.1809
			Phosphorus	7723-14-0	0.065	0.1061
			Silicon (Si)	7440-21-3	99.192	1.8386
SILICON DIE	1.854		Non-hazardous Metal	Proprietary	0.808	0.0150
			Silver	7440-22-4	76.000	0.0904
DIE ATTACH EPOXY	0.119		Acrylic Resin	Proprietary	8.000	0.0095
			Acrylate	Proprietary	5.500	0.0065
			Polybutadiene derivative	Proprietary	5.500	0.0065
			Epoxy resin	Proprietary	2.500	0.0030
			Additive	Proprietary	1.000	0.0012
			Butadiene copolymer	Proprietary	1.000	0.0012
			Peroxide	Proprietary	0.500	0.0006
			Gold(Au)	7440-57-5	99.990	1.0895
GOLD WIRE	1.090		Impurities	-	0.010	0.0001
			Tin (Sn)	7440-31-5	99.990	6.1744
SOLDER PLATING	6.175		Impurity	-	0.010	0.0006

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC  and  China RoHS Directive SJ/T11363-2006	<b>Declaration Statement:</b>	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.  
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.